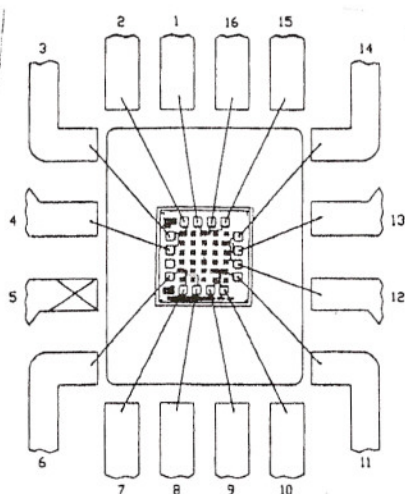




# Sierra Components, Inc.

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Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



REV: 0 (3/23/94)  
DIE SIZE(U): X=1320 Y=1340  
THICKNESS (MIL S/U): 15 / 380  
DIE ATTACH MTRL: SILVER GLASS  
WIRE BOND MTRL: 1.25 MIL AL

**Topside Metal: Al**  
**Backside: Si**  
**Backside Potential:**  
**Mask Ref:**  
**Bond Pads : .004" min**

**APPROVED BY: CD**  
**MFG: Harris**

**DIE SIZE : .051" x .053"**  
**THICKNESS: .014"**

**DATE: 2/5/01**  
**P/N: HFA3127**

DG 10.1.2  
Rev A 3-4-99